

N-CHANNEL ENHANCEMENT MODE MOSFET

General Description

RMP8N70 is an N-channel enhancement mode MOSFET, which uses the self-aligned planar process and improved terminal technology, reducing the conduction loss, enhancing the avalanche energy.

MAIN CHARACTERISTICS

| | | |
|-------------------|-----|----|
| V _{DSS} | 700 | V |
| I _D | 8 | A |
| R _{DSON} | 1.3 | Ω |
| C _{rss} | 13 | pF |

FEATURES

- Low Crss
- Low gate charge
- Fast switching
- Improved ESD capability
- Improved dv/dt capability
- 100% avalanche energy test

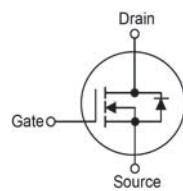
APPLICATIONS

- High efficiency switch mode power supplies
- Electronic lamp ballasts
- UPS

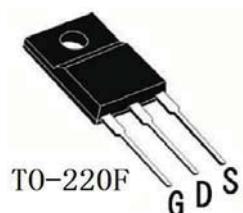
Package Marking And Ordering Information

| Device | Device Package | Marking |
|-----------|----------------|---------|
| RMP8N70TI | TO-220F | 8N70 |
| RMP8N70T2 | TO-220 | 8N70 |

Symbol



Package



MAXIMUM RATINGS (T_c=25°C)

| Parameter | Symbol | | Value | Unit |
|---|--|-----------------------|---------------|------|
| Drain-Source Voltage | V _{DSS} | | 700 | V |
| Continues Drain Current | I _D | T _c =25°C | 8* | A |
| | | T _c =100°C | 4.5* | |
| Plused Drain Current (note 1) | I _{DM} | | 30 | A |
| Gate-to-Source Voltage | V _{GS} | | ±30 | V |
| Single Pulsed Avalanche Energy (note2) | E _{AS} | | 345 | mJ |
| Avalanche Current (note 1) | I _{AR} | | 8.0 | A |
| Repetitive Avalanche Energy (note 1) | E _{AR} | | 12 | mJ |
| Peak Diode Recovery (note3) | dv/dt | | 4.5 | V/ns |
| Power Dissipation | P _D T _c =25°C | TO-220 | 147 | W |
| | | TO-220F | 48 | |
| Power Dissipation Derating Factor | P _{D(DF)} Above 25°C | TO-220 | 1.18 | W/°C |
| | | TO-220F | 0.38 | |
| Operating and Storage Temperature Range | T _J , T _{STG} | | 150, -55~+150 | °C |
| Maximum Temperature for Soldering | T _L | | 300 | °C |

THERMAL CHARACTERIASTIC

| Parameter | Symbol | | Max | Unit |
|---|----------------------|---------|------|------|
| Thermal Resistance, Junction to Case | R _{th(j-c)} | TO-220 | 0.85 | °C/W |
| | | TO-220F | 2.6 | |
| Thermal Resistance, Junction to Ambient | R _{th(j-A)} | TO-220 | 62.5 | °C/W |
| | | TO-220F | 62.5 | |

* Drain current limited by maximum junction temperature

ELECTRICAL CHARACTERISTICS

| Off-Characteristics | | | | | | |
|---|------------------------------|---|-----|------|------|--------------|
| Parameter | Symbol | Tests Conditions | Min | Type | Max | Unit |
| Drain-Source Breakdown Voltage | BV_{DSS} | $I_D=250\mu A, V_{GS}=0V$ | 700 | - | - | V |
| Breakdown Voltage Temperature Coefficient | $\Delta BV_{DSS}/\Delta T_J$ | $I_D=250\mu A$, referenced to $25^\circ C$ | - | 0.7 | - | $V/^\circ C$ |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=700V, V_{GS}=0V, T_c=25^\circ C$ | - | - | 1 | μA |
| | | $V_{DS}=560V, T_c=125^\circ C$ | - | - | 10 | |
| Gate-body leakage current, forward | I_{GSSF} | $V_{DS}=0V, V_{GS}=30V$ | - | - | 100 | nA |
| Gate-body leakage current, reverse | I_{GSSR} | $V_{DS}=0V, V_{GS}=-30V$ | - | - | -100 | nA |

| On-Characteristics | | | | | | |
|-----------------------------------|--------------|--------------------------------|-----|------|-----|----------|
| Parameter | Symbol | Tests Conditions | Min | Type | Max | Unit |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2.0 | - | 4.0 | V |
| Static Drain-Source On-Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=4.0A$ | - | 1.3 | 1.6 | Ω |
| Forward Transconductance | g_f | $V_{DS}=40V, I_D=4.0A$ (note4) | - | 7.0 | - | S |

| Dynamic Characteristics | | | | | | |
|------------------------------|-----------|-----------------------------------|-----|------|------|------|
| Parameter | Symbol | Tests Conditions | Min | Type | Max | Unit |
| Input capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V, f=1.0MHz$ | - | 1050 | 1980 | pF |
| Output capacitance | C_{oss} | | - | 107 | 212 | pF |
| Reverse transfer capacitance | C_{rss} | | - | 13 | 22 | pF |

| Switching Characteristics | | | | | | |
|---------------------------|--------------|--|-----|------|-----|------|
| Parameter | Symbol | Tests Conditions | Min | Type | Max | Unit |
| Turn-On delay time | $t_{d(on)}$ | $V_{DD}=350V, I_D=8A, R_G=25\Omega$ (note 4, 5) | - | 35 | 75 | ns |
| Turn-On rise time | t_r | | - | 80 | 170 | ns |
| Turn-Off delay time | $t_{d(off)}$ | | - | 130 | 265 | ns |
| Turn-Off Fall time | t_f | | - | 85 | 180 | ns |
| Total Gate Charge | Q_g | $V_{DS}=560V, I_D=8A, V_{GS}=10V$ (note 4, 5) | - | 45 | 60 | nC |
| Gate-Source charge | Q_{gs} | | - | 7.6 | - | nC |
| Gate-Drain charge | Q_{gd} | | - | 12 | - | nC |

| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
|--|----------|--|-----|------|-----|---------|
| Parameter | Symbol | Tests Conditions | Min | Type | Max | Unit |
| Maximum Continuous Drain-Source Diode Forward Current | | I_S | - | - | 8 | A |
| Maximum Pulsed Drain-Source Diode Forward Current | | I_{SM} | - | - | 30 | A |
| Drain-Source Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_S=8A$ | - | - | 1.4 | V |
| Reverse recovery time | t_{rr} | $V_{GS}=0V, I_S=8A$ $dI_F/dt=100A/\mu s$ (note 4) | - | 380 | - | ns |
| Reverse recovery charge | Q_{rr} | | - | 3.0 | - | μC |

Notes:

- 1: Pulse width limited by maximum junction temperature
- 2: $L=10mH, I_{AS}=8A, V_{DD}=50V, R_G=25\Omega$, Starting $T_J = 25^\circ C$
- 3: $I_{SD} \leq 8A, dI/dt \leq 300A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ C$
- 4: Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
- 5: Essentially independent of operating temperature

RATING AND CHARACTERISTICS CURVES (RMP8N70TI/T2)

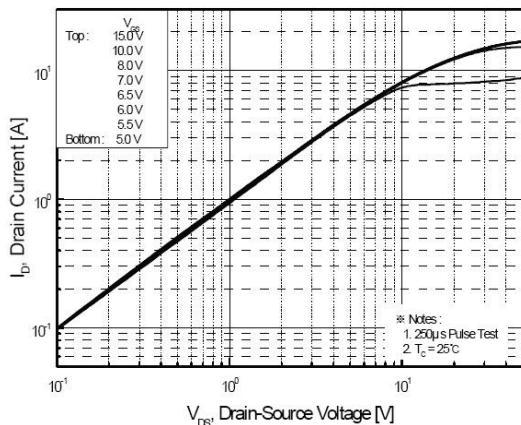


Fig. 1 On-State Characteristics

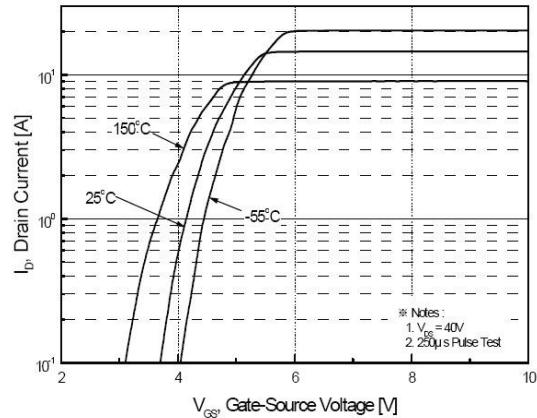


Fig. 2 Transfer Characteristics

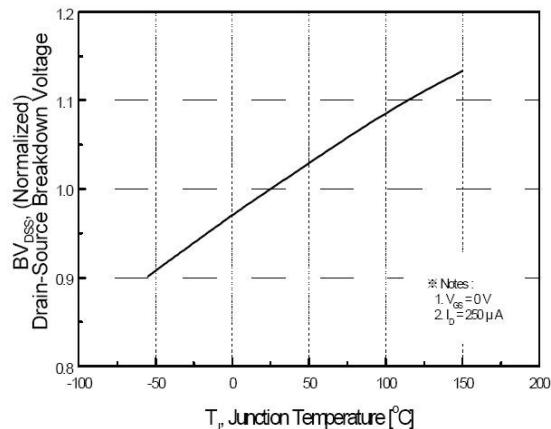


Fig. 3 Breakdown Voltage Variation vs Temperature

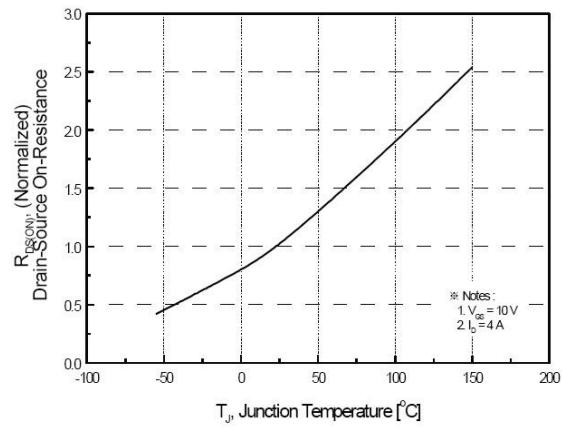


Fig. 4 On-Resistance Variation vs Temperature

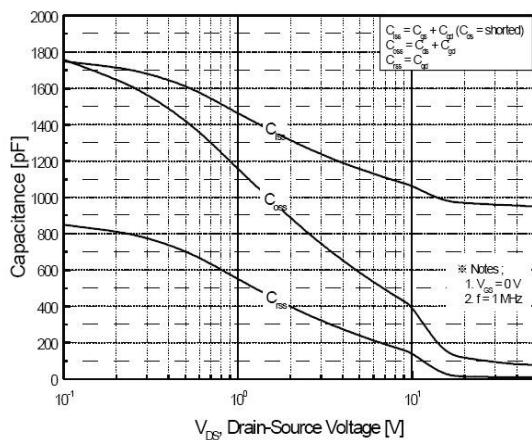


Fig. 5 Capacitance Characteristics

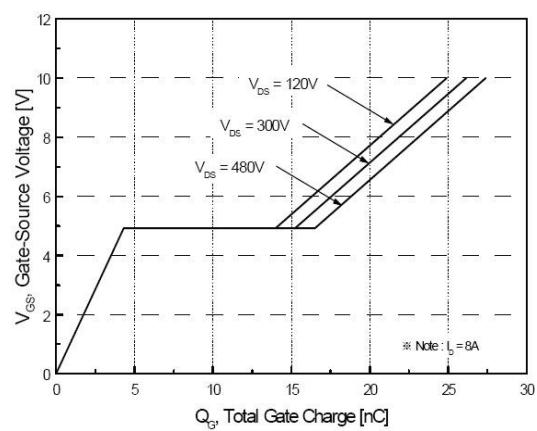


Fig. 6 Gate Charge Characteristics

RATING AND CHARACTERISTICS CURVES (RMP8N70TI/T2)

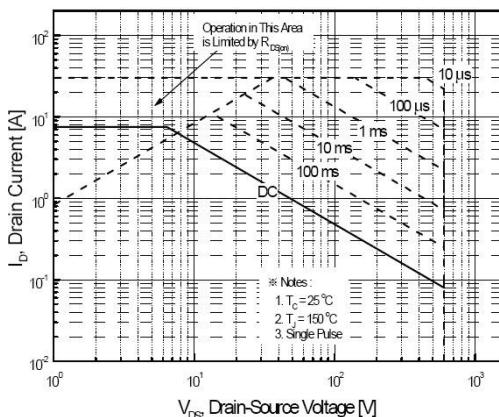


Fig. 7 Maximum Safe Operating Area

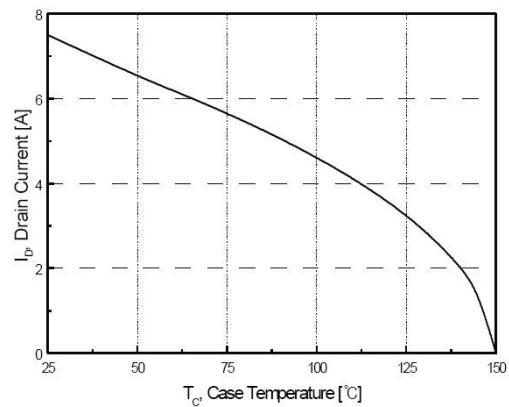


Fig. 8 Maximum Drain Current vs Case Temperature

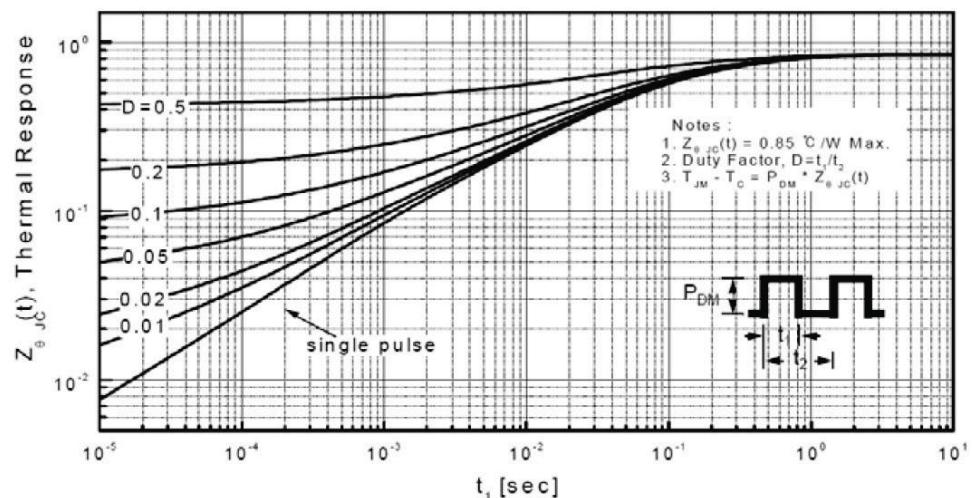


Fig. 9 Transient Thermal Response Curve(TO-220/TO-262)

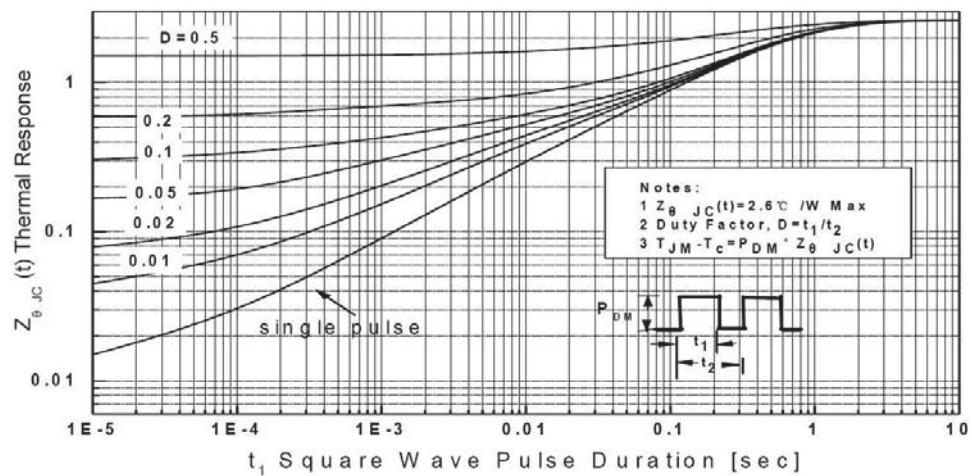


Fig. 10 Transient Thermal Response Curve(TO-220F)

TEST CIRCUITS AND WAVEFORMS

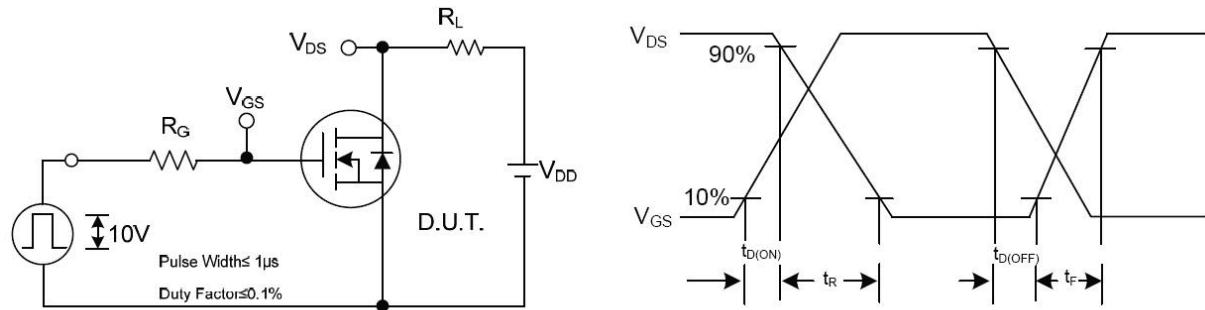


Fig.11 Resistive Switching Test Circuit & Waveforms

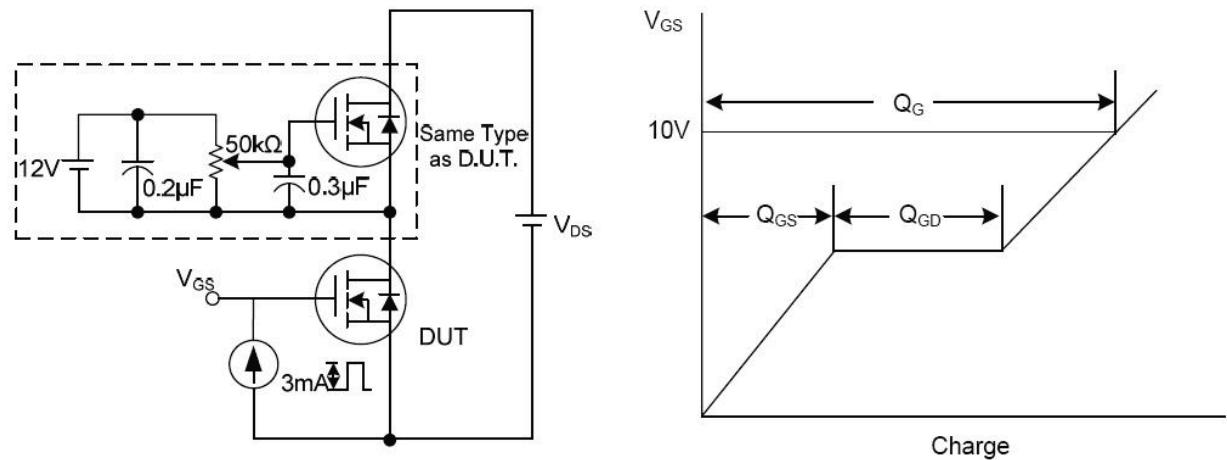


Fig.12 Gate Charge Test Circuit & Waveform

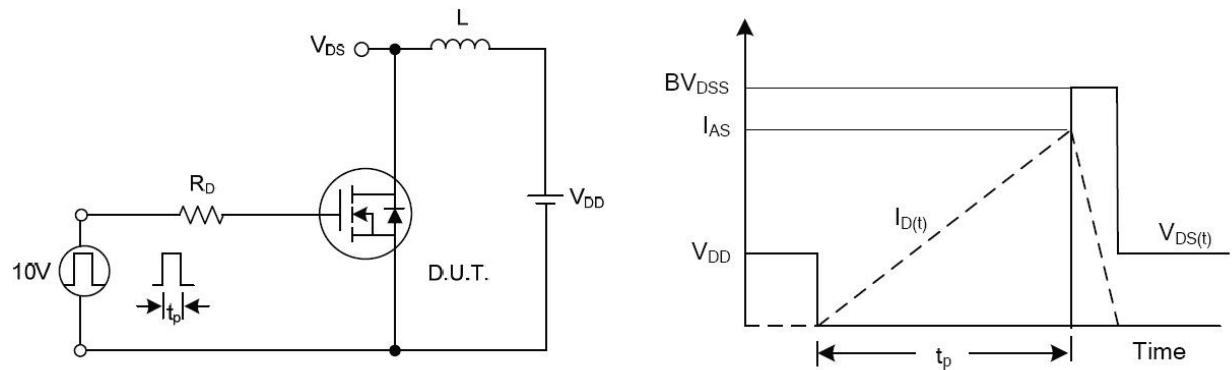


Fig.13 Unclamped Inductive Switching Test Circuit & Waveforms

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